

Technology Features

Conductor Widths	Development	Reduced Yield	Standard
Print And Etch	0.08 mm	0.10 mm	0.125 mm
Inner & Outer Layers	0.07 mm	0.125 mm	0.150 mm
Conductor Spacing	0.07 mm	0.125 mm	0.150 mm
Pth Board Thickness Minimum	<0.5 mm	<0.8 mm	< 1.6 mm
Pth Board Thickness Maximum	> 5.00 mm	> 5.00 mm	> 3.2 mm
Multilayer			
Layer Count	24 +	18 - 24	4 - 18
Min Thickness	0.30 mm	0.40 mm	0.80 mm
Max Thickness	> 5.00 mm	> 5.00 mm	3.20 mm
Bow & Twist	<0.5%	<0.5%	0.7%
Hole Sizes			
Min Mechanically Drilled	0.15 - 0.20 mm	0.20 - 0.30 mm	0.35 mm
Min Laser Drilled	0.07 mm	0.08 mm	0.10 mm
Npth Size Tol	+/- 0.025 mm	+/- 0.25 mm	+/- 0.05 mm
Pth Size Tol	+/- 0.0375 mm	+/- 0.05 mm	+/- 0.75 mm
Positional Tol	+/- 0.045 mm	+/- 0.05 mm	+/- 0.075 mm
2nd Stage Drill Tol	+/- 0.10 mm	+/- 0.15 mm	+/- 0.175 mm
Plating Down Holes	20um MIN	20um MIN	20um MIN
Controlled Impedance	All types available single ended and differential. All impedance values, 28 Ω , 50 Ω , 75 Ω , 100 Ω Tolerances Normal 10% Advanced 5% Specials 3%		
Aspect Ratio	> 10 : 1	6 : 1 - 10 : 1	4 : 1 - 6 : 1
Aspect Ratio Blind Microvia	1.5 : 1	1.2 : 1	1 : 1